

# SOT517-1

plastic surface mounted single in-line power package; 13 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	SMS13P
<b>Package type industry code</b>	SMS13P
<b>Package style descriptive code</b>	SMS (surface-mounted single in-line)
<b>Package style suffix code</b>	P (power)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

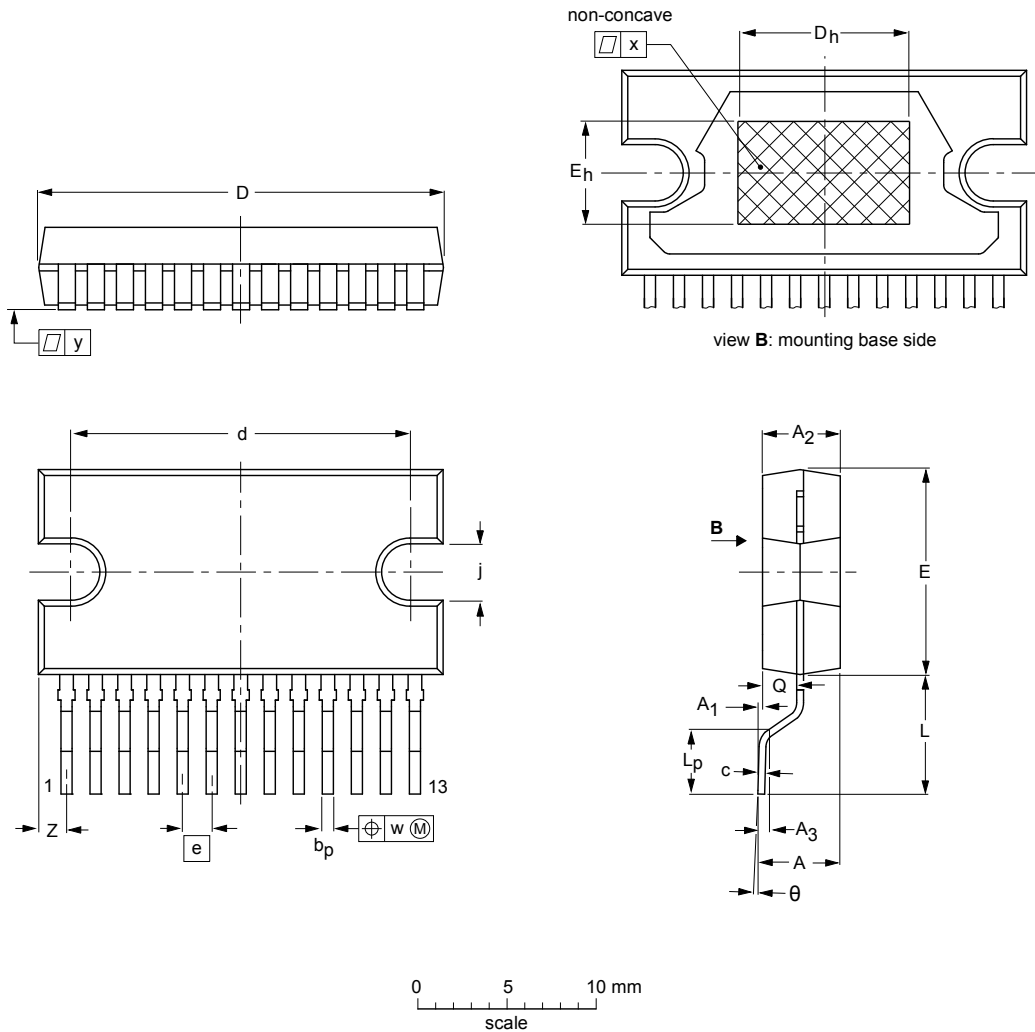
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	23.6	-	23.8	24	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	4.2	-	4.55	4.9	mm
A <sub>2</sub>	package height	4.4	-	4.5	4.6	mm
n <sub>2</sub>	actual quantity of termination	-	-	13	-	



2. Package outline

SMS13P: plastic surface mounted single in-line power package; 13 leads

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	E <sub>h</sub>	j	L	L <sub>p</sub>	Q	w	x	y	z <sup>(1)</sup>	θ
mm	4.9 4.2	0.3 0.0	4.6 4.4	0.25	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	1.7	6	3.4 3.1	7.4 6.6	3.4 2.8	2.1 1.8	0.25	0.03	0.15	2.00 1.45	3° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT517-1						-99-12-17- 03-03-12

Fig. 1. Package outline SMS13P (SOT517-1)

### 3. Legal information

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